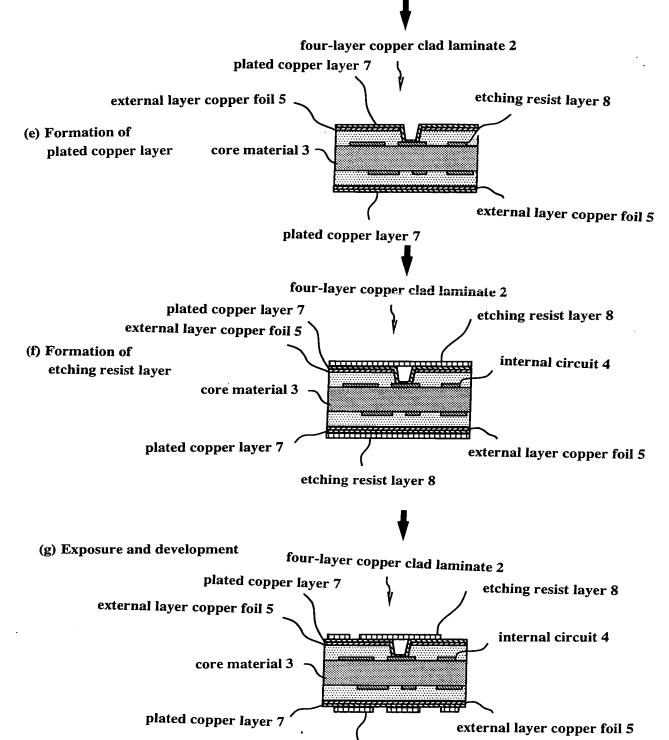


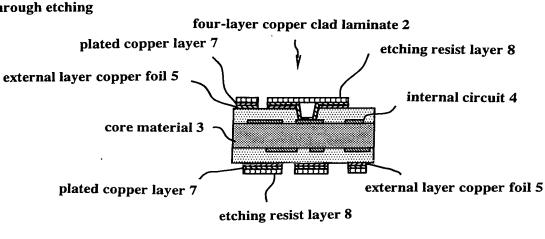
FIG. 2





etching resist layer 8

(h) Formation of a circuit through etching



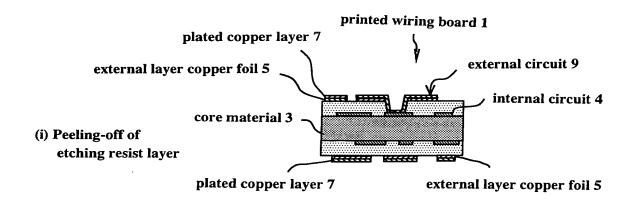


FIG. 4

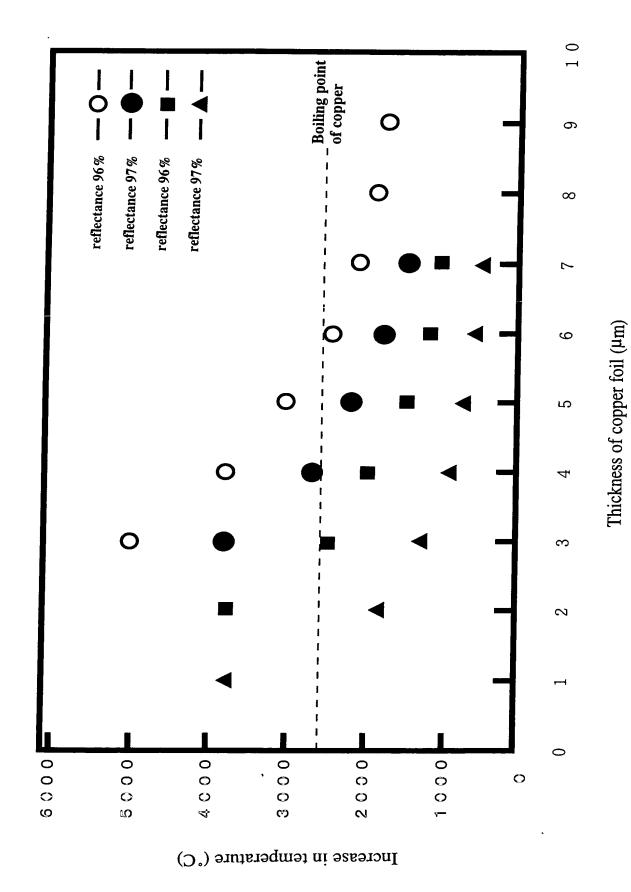
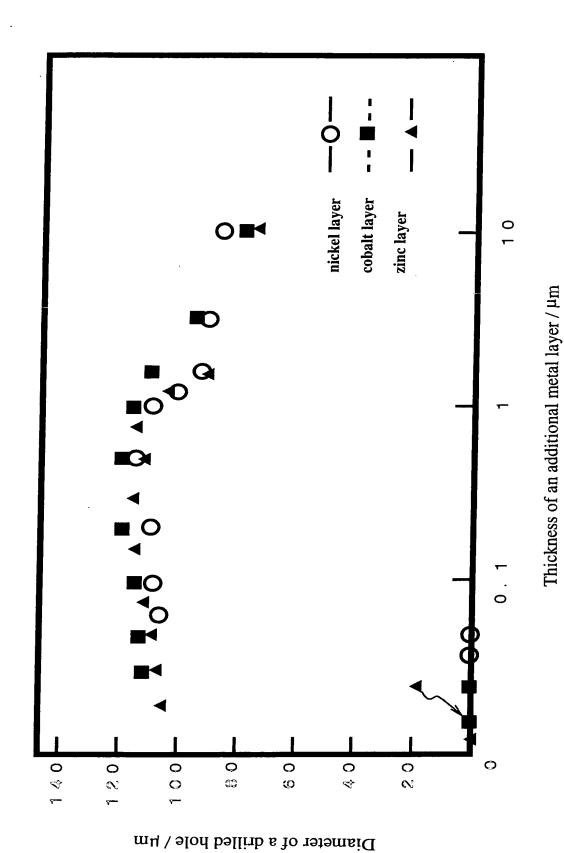
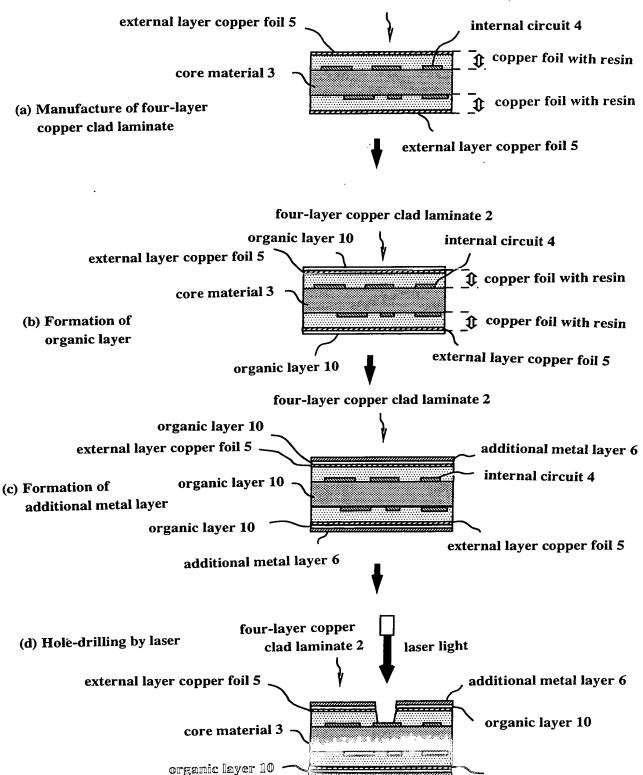


Fig. S



## FIG. 6

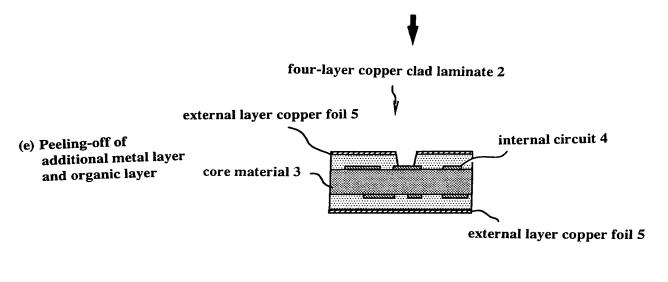
## four-layer copper clad laminate 2



additional metal layer 6

external layer copper foil 5

FIG. 7



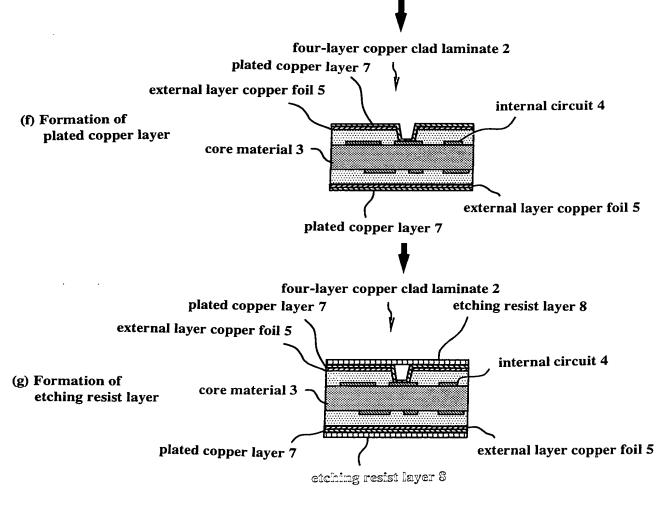




FIG. 8

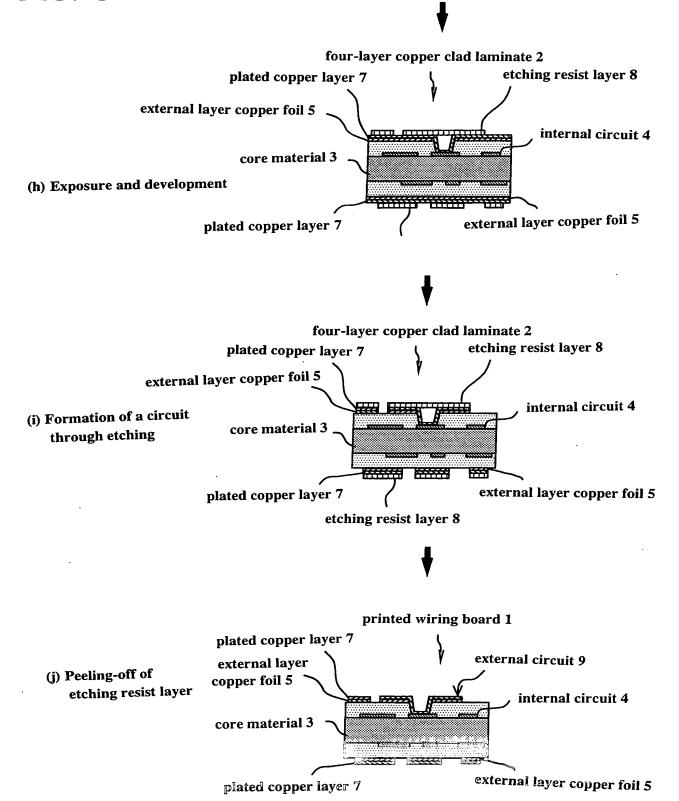
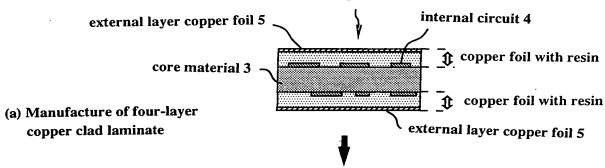


Fig. 9

## four-layer copper clad laminate 2



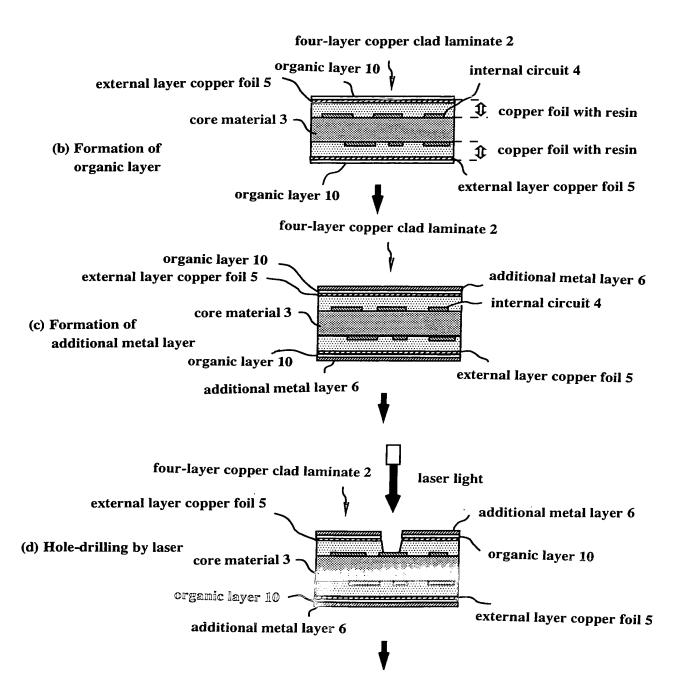


FIG. 10

## four-layer copper clad laminate 2 plated copper layer 7 organic layer 10 additional metal layer 6 external layer copper foil 5. internal circuit 4 core material 3 (e) Formation of external layer plated copper layer copper foil 5 additional metal layer 6 organic layer 10 plated copper layer 7 four-layer copper clad laminate 2 plated copper layer 7 external layer copper foil 5 (f) Peeling-off of internal circuit 4 additional metal layer and organic layer core material 3 external layer copper foil 5 four-layer copper clad laminate 2 etching resist layer 8 plated copper layer 7 external layer copper foil 5 internal circuit 4 (g) Formation of etching resist layer core material 3 external layer copper foil 5



etching resist layer 8

FIG. 11

